

Final Product/Process Change Notification Document #: FPCN22039XB Issue Date: 23 May 2018

Title of Change:	Qualification of ON Semiconductor Mountain Top, USA facility as an additional wafer fab location for MV5 Technology.			
Proposed first ship date:	30 August 2018 or earlier upon customer approval			
Contact information:	Contact your local ON Semiconductor Sales Office or Yuna Im < <u>yuna.im@onsemi.com</u> >			
Samples:	Contact your local ON Semiconductor Sales Office or < <u>PCN.Samples@onsemi.com</u> >			
Additional Reliability Data	Contact your local ON Semiconductor Sales Office or Youngchul Lee< <u>youngchul.lee@onsemi.com</u> >			
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>			
Change Part Identification	Affected parts will be identified with a date code of WW07'18 or later			
Change category:	✓ Wafer Fab Change			
Change Sub-Category(s): Manufacturing Site Cha Manufacturing Process		Datasheet/Product Doc change Shipping/Packaging/Marking Other:		
Sites Affected:	ON Semiconductor Sites: ON Mountain Top, PA External Foundry/Subcon Sites: None			
Description and Purpose: This is a Final Change Notification to inform customers of the qualification of ON Semiconductor Mountain Top, USA facility as an additional wafer fab location for MV5 Technology.				
At the expiration of this notification, all products listed here will be dual sourced from its current ON Semiconductor wafer fab in Bucheon, Korea.				
	Before Change Description	After Change Description		
Fab site	ON Bucheon, Korea	ON Bucheon, Korea		

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Reliability Data Summary:

DEVICE NAME: FDMS86150

RMS: 45933

PACKAGE: PQFN56C

Test	Specification	Condition	Interval	Results
PC	JEDS22 A113	Performed prior to TC, UHAST, HAST and IOL		0/327
HTRB	MILSTD750-1 method M1038A	Tj=150C, bias=80V	1008 hrs	0/80
HTGB	JESD22 A108	Ta=150C, bias=20V	1008 hrs	0/80
HTSL	JESD22 A108	Ta=150C	1008 hrs	0/82
TC	JESD22 A104; Q101 appendix 6	T air= -55C to 150C, t dwell > 15 min	1000 cycles	0/85
UHAST	JESD22 A118	Ta=130C, RH=85%, no bias	96 hrs	0/82
HAST	JESD22 A110	Ta=130C, RH=85%, bias=42V	96 hrs	0/80
IOL	MIL-STD-750 Method 1037	Ta=25C, delta Tj=100C, ton=toff=2min	15000 cycles	0/80
RSH	JESD22 B106	Per AEC - Q101		0/30

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Standard Parts:

Part Number	Qualification Vehicle	
FDMS86150		
FDMS86150A		
FDMS86200		
FDS86242		
FDMS86101	FDMS86150	
FDMS86101_SN00155		
FDMS86101_SN00235		
FDMS86322		
PCF86101W		
FDMS86101DC		

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